

# THERMAL OXIDE PROCESS

Oxide Thickness	Target Thickness Tolerance	Typical Furnace Temperature Range
<500 A Dry	±10%	800°C -900°C ±10%
1KA-2KA Dry	±10%	950°C ±10%
2KA-5KA Wet	±5%	1000°C ±10%
5KA-10KA Wet	±5%	1000°C ±10%
10KA-20KA Wet	±5%	1000°C ±10%

WIWNU: Wafer-within-Wafer Non-Uniformity: ±5% @ Range

## Wafer Size

mm	Inches
100	4
125	5
150	6
200	8
300	12

## Process Flow

Inspection	Criteria
Visual: Finger Prints, Chips, Cracks, Films	100% Accept/0 Reject
Pre-Clean 1: SRD: DI Water, Spin Rinse, Dry	100% Upon Customer Request
Pre-Clean 2: SC1-SC2	100% Upon Customer Request
Pre-Clean 3: Scrub, Low Particle Clean	100% Upon Customer Request
Oxidation	100% ± Thickness Tolerance
Post Measurement	Wafer Map, 1 Per Cassette As Standard
Data Package Prepared	
Visual Inspection	100% Accept/0 Reject
Final Quality Inspection	Review Wafer Map Thickness, WIWNU, Data
Packaging & Shipping	Wafers are double bagged in a clean box, labeled, and shipped.

**Note:**

- Upon inspection of wafers, additional cleaning may be required. Customer will be notified for disposition of material to receive the following:
  - SRD, Spin, Rinse Dry
  - SC1/SC2
- Additional processing and or cleaning may result in an additional charge.
- Additional Wafer Maps upon request.